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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: § Docket No.: 24061.36 (2002-0939)
Hui Lin Chang §
§ Customer No. 42717
Serial No.: 10/696,254 §
§ Conf. No.: 7076
Filed: October 29, 2003 §
§
For: Insulating Layer Having Decreased §
Dielectric Constant and Increased §
Hardness §

TRANSMITTAL

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Enclosed for filing in the above-identified patent application is:

1. Power of Attorney for Patent Application with copy of executed Assignment;
2. This transmittal; and
3. Return receipt postcard.

Applicant believes no fee is due. However, the Director is authorized to charge any deficiency fees or credit any overpayments to Deposit Account No. 08-1394 of Haynes and Boone, LLP.

Respectfully submitted,

David M. O'Dell
Reg. No. 42,044

Date: 8-25-05

HAYNES AND BOONE, LLP
901 Main Street, Suite 3100
Dallas, Texas 75202-3789
Telephone: 972-739-8635
Facsimile: 214-200-0853

Customer Number: 42717

CERTIFICATE OF FACSIMILE

I hereby certify that this correspondence is being sent via facsimile, 703-308-7751, addressed to the Office of Initial Patent Examination, Commissioner For Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on the date indicated below:

Kristina Parra

Name

August 25, 2005

Date



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: § Docket No.: 24061.36
Hui Lin Chang § (TSMC2002-0939)

Serial No.: 10/696,254 § Customer No.: 42717

Filed: October 29, 2003 § Group Art Unit: 2811

For: INSULATING LAYER HAVING § Examiner: To Be Determined
DECREASED DIELECTRIC
CONSTANT AND INCREASED
HARDNESS §

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

POWER OF ATTORNEY FOR PATENT APPLICATION

As a representative of the Assignee, Taiwan Semiconductor Manufacturing, Co. Ltd., I hereby appoint the following attorneys to prosecute the above-identified application and to transact all business in the United States Patent and Trademark Office in connection therewith:

Practitioners associated with the Customer Number

42717

Please direct all correspondence and telephone calls to the address associated with the above-mentioned Customer Number.

The undersigned representative for the Assignee certifies that the assignee is the assignee of the entire right, title and interest in the above-identified patent application. A copy of the assignment or other documents in the chain of title are attached.

Executed the _____ day of _____, 2005.

Taiwan Semiconductor Manufacturing Company, Ltd.



Chien Wei Chou
Director, IP Division

A S S I G N M E N T

WHEREAS, we

(1) Hui Lin Chang of Taiwan, R.O.C.

have invented certain improvements in

**INSULATING LAYER HAVING DECREASED DIELECTRIC CONSTANT AND
INCREASED HARDNESS**

for which we have executed an application for Letters Patent of the United States of America, of even date herewith; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 6, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

First Inventor Name: Hui Lin Chang
Residence Address:
58 Ta-Hsueh road, 10F-4, Hsinchu 30050, Taiwan

Dated: 10/03/03

Hui Lin Chang

Hui Lin Chang
Inventor Signature

Dated: 10/03/03

Witness Signature

Witness Name: Tzu-Jen Chou